# **Technical Information**



# PURPEKS 214

# **Product Information:**

PURPEKS 214 is a Reactive Polyurethane Hot Melt adhesive which cross-links through air moisture.

#### **Application Areas**

Designed for lamination, general assembly work, assembly bonding of wooden parts, and gluing of textiles and plastics.

## Appearance

Blocks in aluminum laminated flexible packaging (peelable bag)

#### At a Glance

- Reactive hotmelt adhesive system based on polyurethane.

- Medium Open time
- High initial strength
- Chemical cross-linking within few days
- Bond joint turns into a thermoset
- Very high heat resistance (> 150 °C) and cold flexibility
- Excellent water resistance
- Resistant to most solvents

# **Technical Data**

Softening Point, Ring & Ball~55 °CViscosity Brookfield @ 120°C (spindle 27)10.000 – 20.000 cpHeat Resistance>150 °C

# **Application Temperature**

Melter	100 – 140°C
Feeding hoses	100 - 140°C
Application unit	50 - 400°C

\*Since the product will cure when it is exposed to moisture, storage and application must be done under dry conditions. For this reason, the product is delivered in airtight cointainers.

## **Recommended Application Amount**

Wood materials, depending on substrate to be bonded  $50 - 90 \text{ g/m}^2$ 

## Substrate Temperature

Foil temperature has to be 15-35°C and the profile has to be preheated at least at 40°C just before the firs pressing roller in order to achieve the best wetting of the surface.

## Curing

The initial bond strength is sufficient to keep the two substrates bonded together. Nevertheless, the final bonding strength and resistance is achieved after the full curing of the adhesive which depends on substrate and environment humidity.

#### Storage

Store in a cool, dry place in the unopened original container for up to 12 months. (2 kg container for up to 9 months).

#### Packaging

20 kg block in aluminum laminated flexible packaging, in cardboard or metal drums.

200 kg in aluminum laminated flexible packaging in metal drums.

Density (g/cm³):approx. 1.02Curing Time, days2 - 5(\*) Typical properties, not to be used as specification

# Cleaning

Flushing the system with PUR-CLEANER periodically or prior to changing to an alternative reactive hot melt will reduce internal build-up of adhesive residue. Application devices such as wheels and rolls that expose reactive adhesive to the air should be thoroughly flushed at the end of a production run or at any time when there is buildup and gelling. We recommend for the cleaning of the application equipment's PUR-CLEANER. When working with the cleaning agent's safety instructions must be considered. Follow also strictly the instructions of the machine manufacturer.

## Processing

Reactive hotmelt adhesives have a limited thermal stability even when working at the specified working temperatures; therefore, we recommend that after a period of 4 hours without production, that the unit is either switched off, or the set temperatures on the unit be reduced to 60°C. Since the product will cure when it is exposed to moisture, storage and application must be done under dry conditions. For this reason, the product is delivered in airtight containers.

## Safety

The product contains diphenylmethanedisocyanate. Even if the product is applied within the range of the recommended working temperature, the disocyanate has a detectable vapour pressure. When the recommended working temperature is considerably exceeded, hazardous decomposition products may be formed in the application unit; therefore, measures to draw off the vapours need to be taken, e.g. through the provision of extraction equipment. In case of skin contact with the hotmelt, do not try to remove the adhesive from the skin by force. Consult a doctor. Observe the material safety sheets.

Disclaimer:

The statements listed on this publication are according to our best knowledge. The statements do not exonerate the user from their own responsibility to determine that our products are suitable for their processes. They are intended to inform and advise and are subject to influence from the technical process.

This edition of November 14, 2024 replaces all previous editions. With the present edition all older editions are null and void